US00D851611S

(12) **United States Design Patent**
Kurz

(10) **Patent No.: US D851,611 S**
(45) **Date of Patent: ** Jun. 18, 2019**

(54) **SEMICONDUCTOR MODULE**

(71) Applicant: **Infineon Technologies AG**, Neubiberg (DE)

(72) Inventor: **Dorian Kurz**, Solingen (DE)

(73) Assignee: **Infineon Technologies AG**, Neubiberg (DE)

(**) Term: **15 Years**

(21) Appl. No.: **29/541,089**

(22) Filed: **Sep. 30, 2015**

(30) **Foreign Application Priority Data**

Apr. 1, 2015 (EM) 002673699

(51) **LOC (11) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**; D13/158

(58) **Field of Classification Search**
USPC D13/101, 110, 118, 123, 158–162, 173, D13/182, 184, 199
CPC . G05B 15/00; H01H 9/00; H01H 9/02; H01H 9/22; H01H 13/00; H01L 23/48; H01L 23/49; H01L 23/52; H01L 25/07; H01R 13/00; H01R 13/60; H02B 1/00
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

D358,753 S *	5/1995	Yoshida	D13/123
6,731,507 B2 *	5/2004	Varghese	G06F 1/18 312/223.2
6,802,737 B2 *	10/2004	Bergner	H01R 9/2658 439/532
7,397,668 B2 *	7/2008	Sekine	H05K 7/1465 361/728
D621,351 S	8/2010	Huang et al.	
D695,229 S *	12/2013	Ran	D13/158
D737,221 S *	8/2015	Andersson	D13/158
9,099,256 B2 *	8/2015	Gole	
D753,608 S *	4/2016	Chen	D13/162.1
D754,614 S *	4/2016	Chen	D13/162.1
D763,201 S *	8/2016	Burkell	D13/162
D834,544 S *	11/2018	Kurz	D13/182
D834,545 S *	11/2018	Kurz	D13/182
2010/0307895 A1 *	12/2010	Park	H01H 9/02 200/237
2012/0109343 A1 *	5/2012	Shah	G05B 19/409 700/83

* cited by examiner

Primary Examiner — Angela J Lee
Assistant Examiner — Shawn T Gingrich
(74) *Attorney, Agent, or Firm* — Murphy, Bilak & Homiller, PLLC

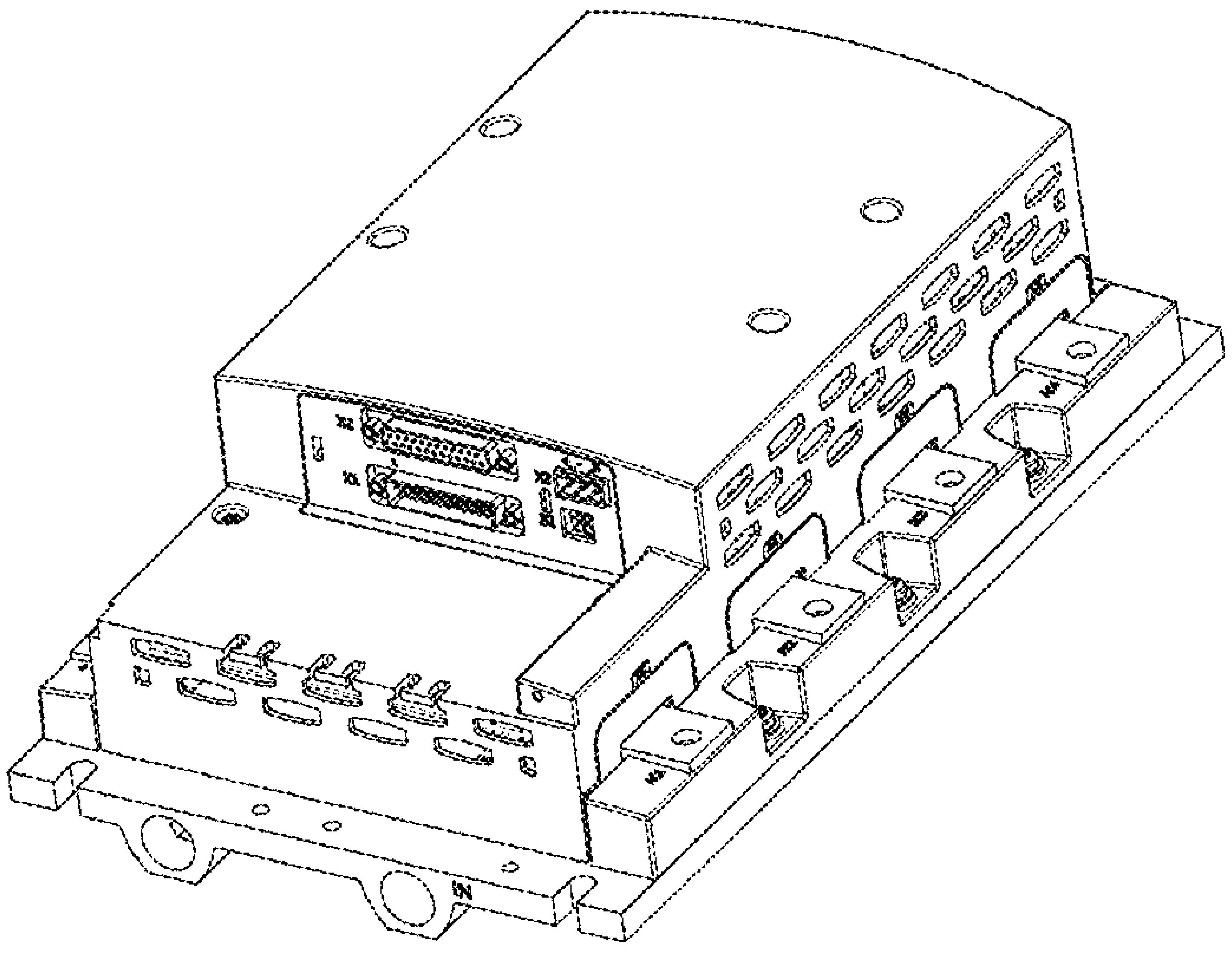
(57) **CLAIM**

The ornamental design for a semiconductor module, as shown and described.

DESCRIPTION

FIG. **1** is a top, front and right side perspective view of the semiconductor module showing my new design;
FIG. **2** is a back side elevational view thereof;
FIG. **3** is a front side elevational view thereof;
FIG. **4** is a left side elevational view thereof;
FIG. **5** is a right side elevational view thereof; and,
FIG. **6** is a top plan view thereof.
The broken line portion of the figure drawings is included to show portions of the article that form no part of the claimed design.
All surfaces not shown form no part of the claimed design.

1 Claim, 6 Drawing Sheets



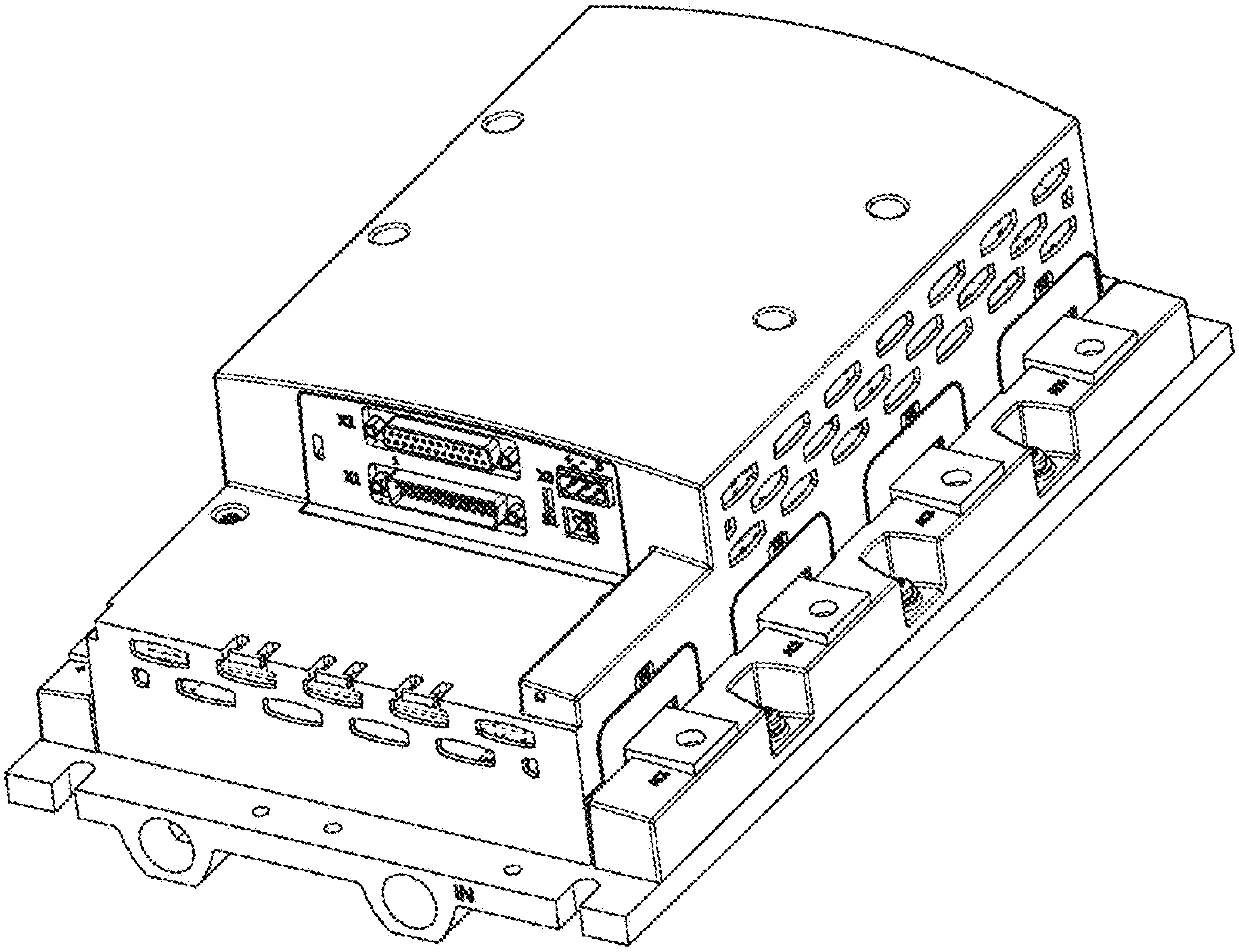


FIG. 1

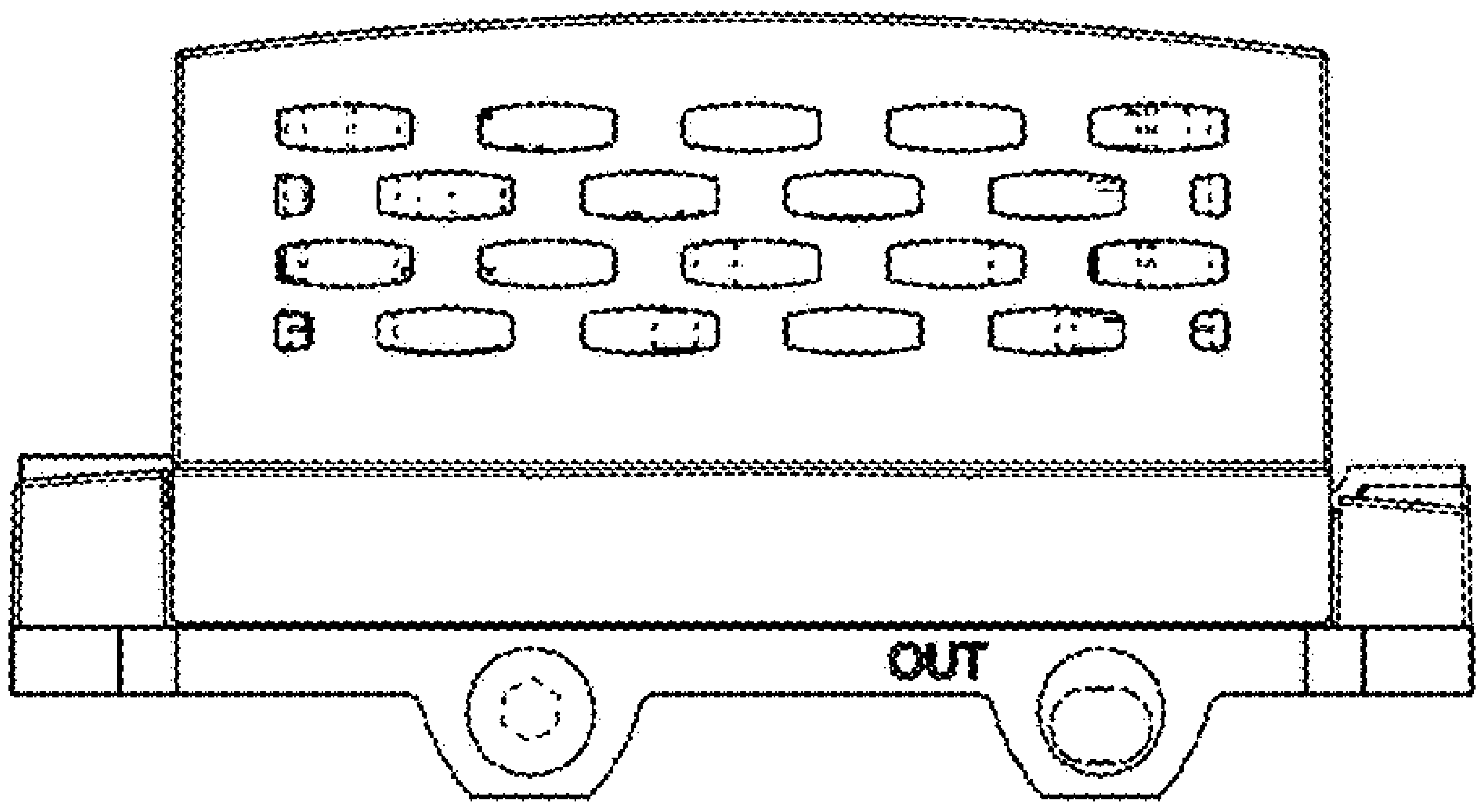


FIG. 2

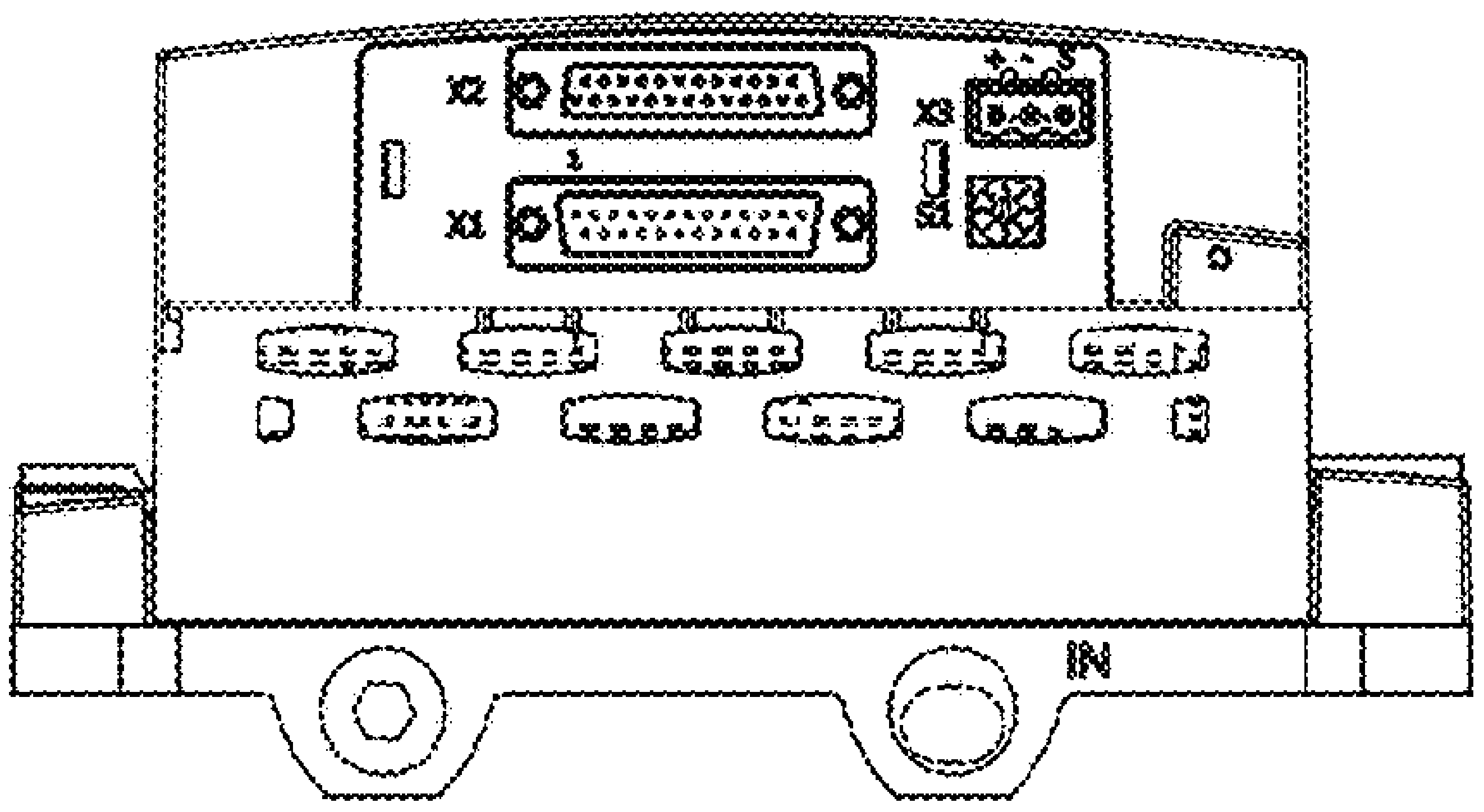


FIG. 3

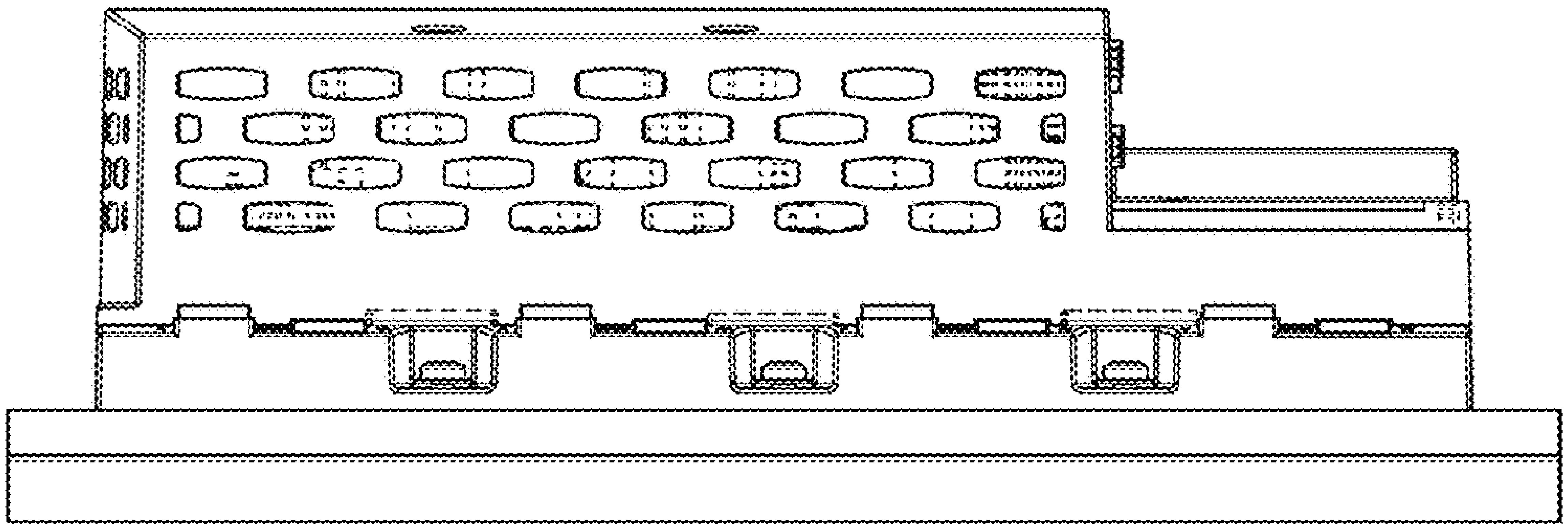


FIG. 4

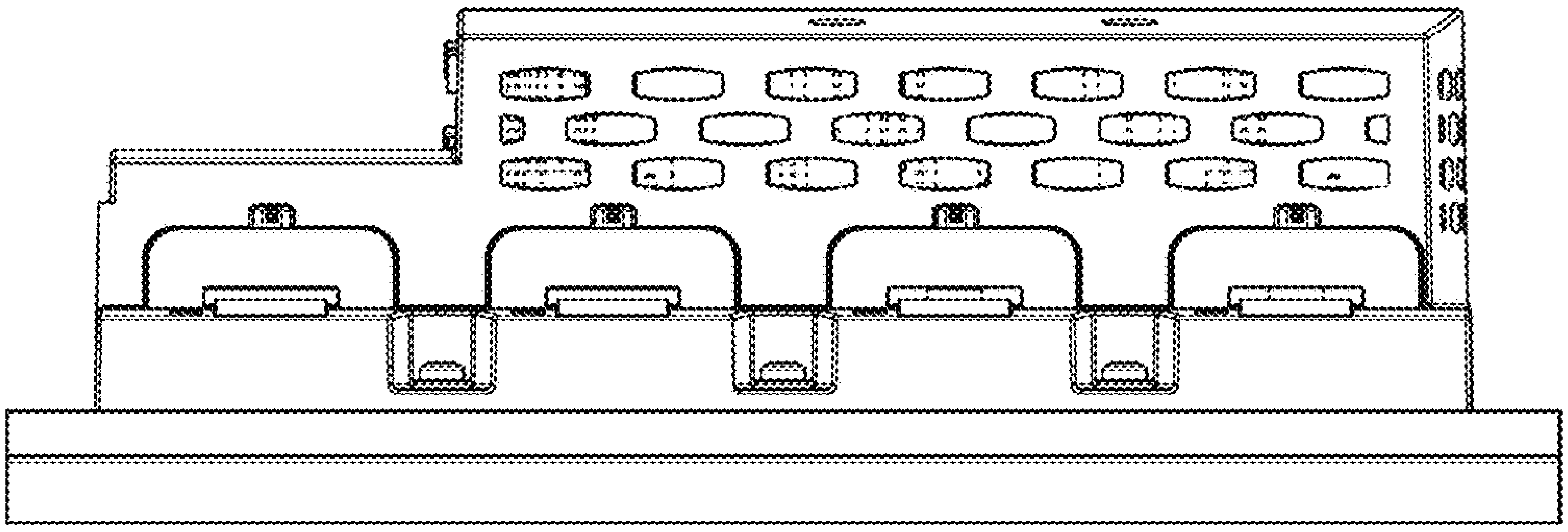


FIG. 5

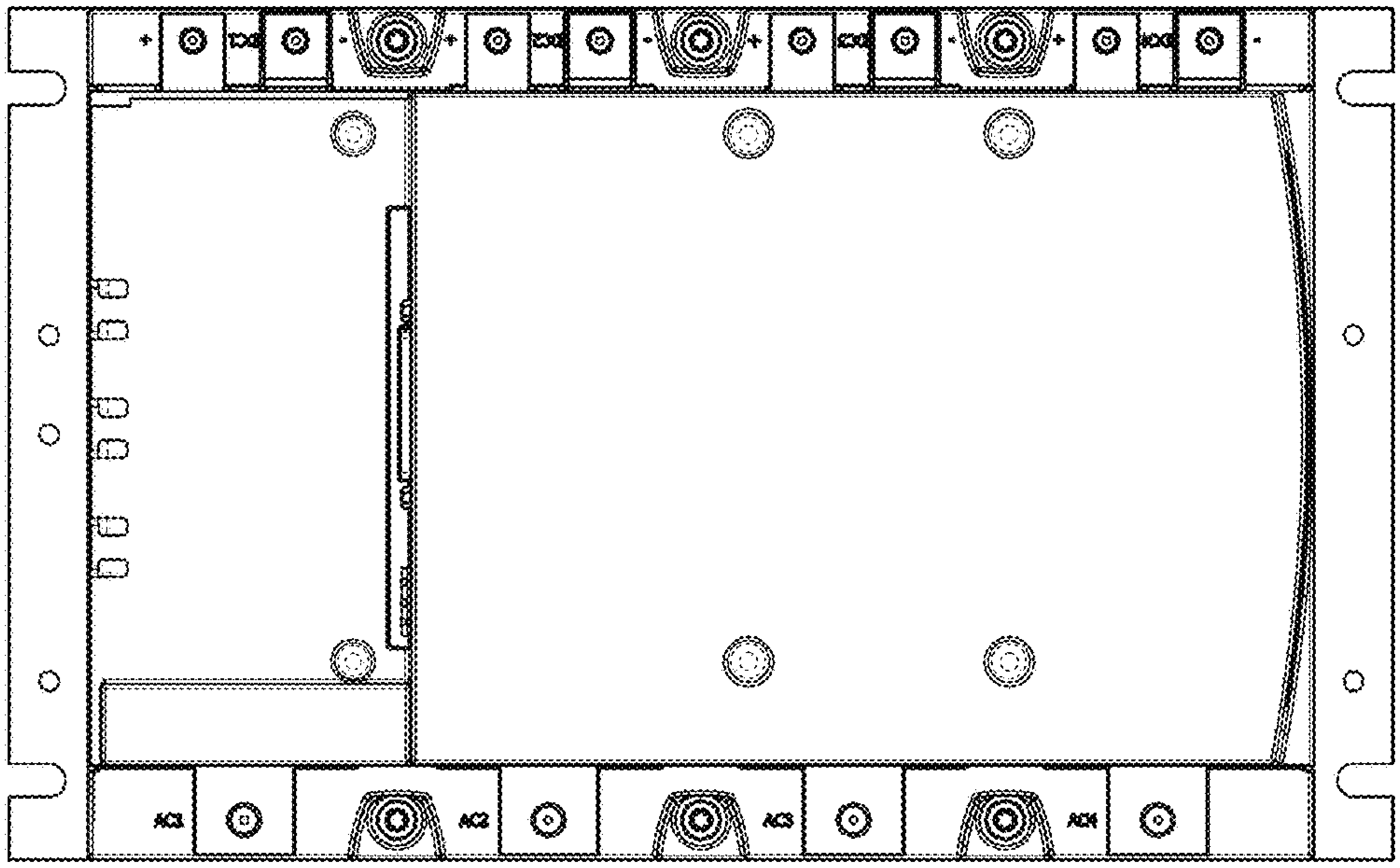


FIG. 6